

Wiring, Printed Certified for Canada - Component

COMPANY

AKA PCB D O O
 Rozna Dolina 54
 Lesce, 4248 Slovenia


E208099

Type	Cond Width		Min Edge	Cond Thk	SS/ DS/	Area Diam	Report date After	Surface Mount	Assembly Solder Process	Solder Limits	Oper Temp	Max	Meets UL796	C	
	mm	mm													mic
Single layer metal base printed wiring boards															
4	0.10	0.10	35	SS	30.0	No	-	-	-	260	10	130	V-0	All	0
5 (ASP 1)	0.10	0.10	35	SS	30	Yes	Yes	260	3	-	-	130	V-0	All	0
Single layer printed wiring boards															
1	0.15	0.23	33	SS	20.6	No	-	-	-	260	10	105	V-0	All	0
3	0.18	0.25	33	SS	20.6	No	-	-	-	270	10	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

ASP 1 - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Marking: Company name or trademark **AKA** or file number and type designation and the Recognized Component Mark for

Canada, . May be followed by a suffix to denote factory identification or flammability classification..

Last Updated on 2024-06-11

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	mm	mm													
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